

New SEMiX[®] package with press-fit contacts

Status update

Up to now SEMIKRON offers SEMiX IGBT and rectifier modules with the established spring technology. Following the customer demand to contact the driver board with press-fit pins, the SEMiX package portfolio will be extended.

The new category is called SEMiX 3p. As the name indicates the footprint is the same as with the current housing size 3s. Like the spring version is coded with an 's', 'p' is the abbreviation for press-fit contacts.



All fixation points regarding heat sink and main terminals are the same compared to existing SEMiX 3s and competitor types. The positions of the auxiliary press-fit contacts are compatible with competing modules using also press-fit contacts or solder pins.

In the beginning only IGBT half-bridge modules in the 1200V class will be offered. The chips used inside will be the medium power IGBT4 (E4) in combination with CAL4 F diodes. For the market introduction three current ratings are planned:

Voltage class	I _{Cnom}	Topology	Type designation	Item number
1200V	300A		SEMiX303GB12E4p	27893012
1200V	450A		SEMiX453GB12E4p	27893026
1200V	600A		SEMiX603GB12E4p	27893036

For the 300A and 450A type the development has already made progress:

- Target data sheets are available on request
- Qualified samples and complete documentation (final data sheets, mounting instructions, technical explanations, product presentation, ...) will be provided in March 2014
- Zero series release is planned for June 2014

For the 600A module more time is needed:

- Target data sheet will be prepared by mid of January 2014
- Qualified samples can be offered in May 2014
- Zero series release is also planned for June 2014

In the meantime mechanical samples of SEMiX 3p can be provided. They are available with number 27899080. Please contact product management before entering your order.